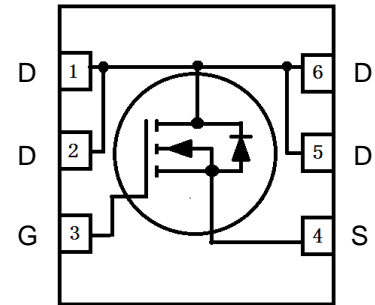
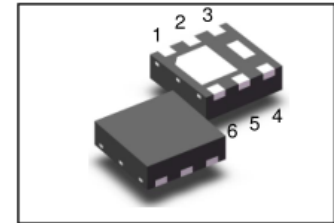


LN2604DT2AG

60V N-Channel Enhancement MOSFET



1. FEATURES

- $V_{DS} = 60\text{ V}$
 $R_{DS(ON)} \leq 35\text{ m}\Omega, V_{GS}@10\text{ V}, I_{DS}@5\text{ A}$
 $R_{DS(ON)} \leq 40\text{ m}\Omega, V_{GS}@4.5\text{ V}, I_{DS}@4\text{ A}$
- Low $R_{DS(ON)}$ trench technology
- Low thermal impedance
- Fast switching speed
- We declare that the material of product are Halogen Free and compliance with RoHS requirements.

2. APPLICATIONS

- DC/DC Conversion
- Power Routing
- Motor Drives

3. ORDERING INFORMATION

Device	Marking	Shipping
LN2604DT2AG	04D	4000/Tape&Reel

4. MAXIMUM RATINGS($T_a = 25^\circ\text{C}$ unless otherwise stated)

Parameter	Symbol	Limits	Unit	
Drain-to-Source Voltage	V_{DSS}	60	V	
Gate-to-Source Voltage	V_{GS}	± 20	V	
Avalanche Current	I_{AS}	10	A	
Avalanche energy $L=0.1\text{ mH}$	E_{AS}	5	mJ	
Continuous Drain Current(Note 1)	I_D	$T_A = 25^\circ\text{C}$	7	A
		$T_A = 70^\circ\text{C}$	4	
Pulsed Drain Current (Note 2)	I_{DM}	28	A	
Power Dissipation(Note 1)	P_D	$T_A = 25^\circ\text{C}$	2	W
		$T_A = 70^\circ\text{C}$	1.5	
Operating Junction and Storage Temperature Range	T_J, T_{STG}	$-55 \sim +150$	$^\circ\text{C}$	

5. THERMAL CHARACTERISTICS

Parameter	Symbol	Value	Unit
Junction-to-Ambient(Note 3)	$R_{\theta JA}$	60	$^\circ\text{C/W}$
Junction-to-Case	$R_{\theta JC}$	20	$^\circ\text{C/W}$

- 1.Surface mounted on "1.5 x 1.5" FR4 board using 1 sq in pad, 2 oz Cu.
- 2.Pulse width limited by maximum junction temperature.

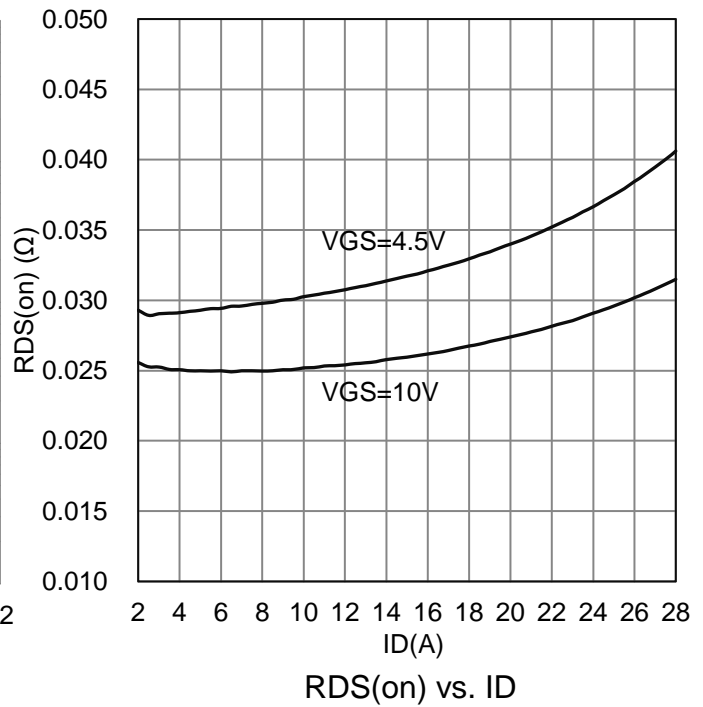
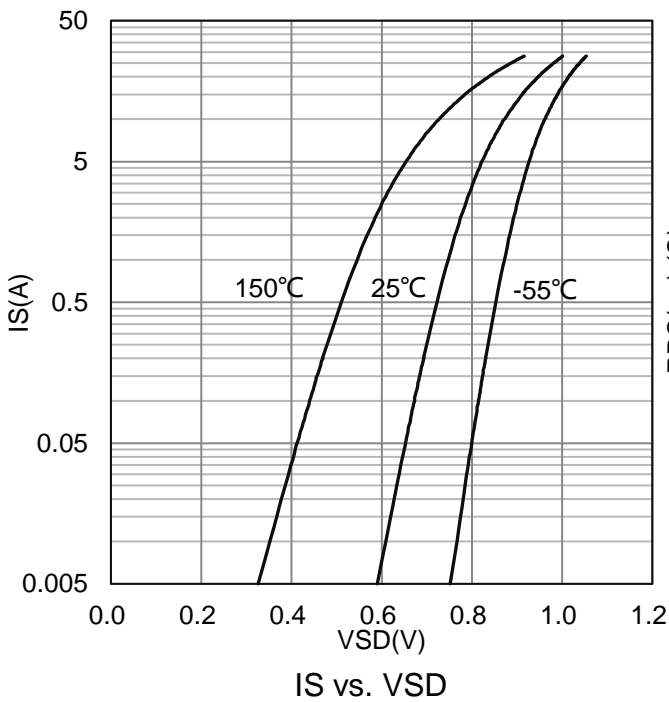
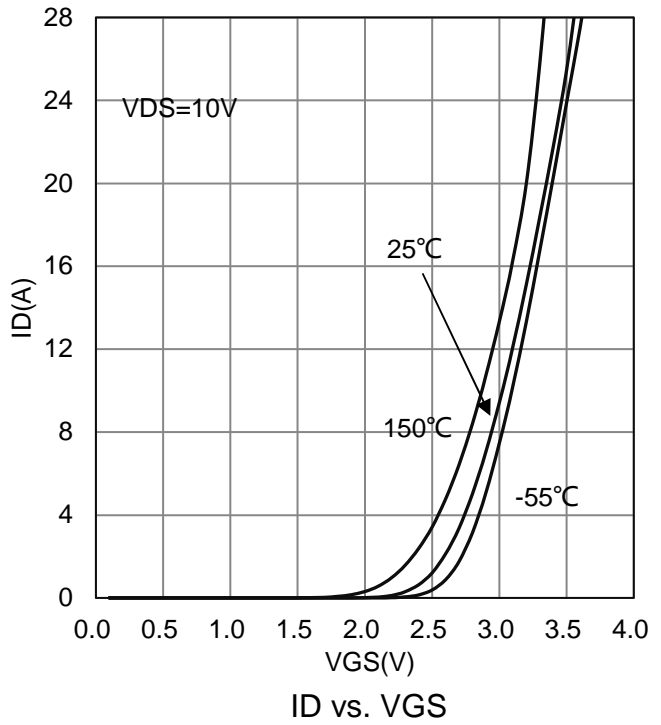
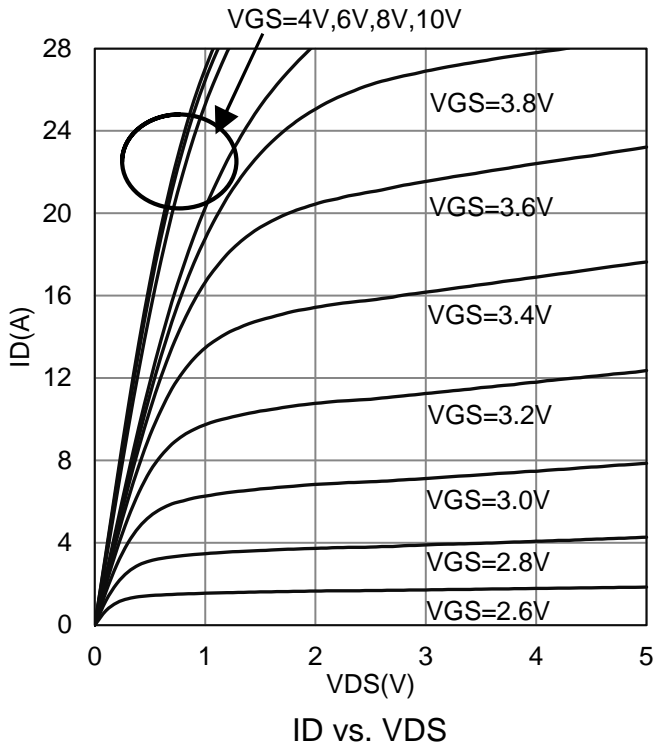
6. ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Static					
Drain-Source Breakdown Voltage (VGS = 0, ID = 250μA)	V(BR)DSS	60	-	-	V
Gate-Source Threshold Voltage (VDS = VGS, ID = 250 μA)	VGS(th)	1	1.9	3	V
Gate-Body Leakage (VDS = 0 V, VGS = ±20 V)	IGSS	-	-	± 10	μA
Zero Gate Voltage Drain Current (VDS = 48 V, VGS = 0 V)	IDSS	-	-	1	μA
Drain-Source On-Resistance(Note 3) (VGS = 10 V, ID = 7 A) (VGS = 4.5 V, ID = 5 A)	RDS(on)	-	23 32	35 40	mΩ
Diode Forward Voltage(Note 3) (IS = 1.9 A, VGS = 0 V)	VSD	-	0.78	1.5	V
Dynamic(Note 4)					
Total Gate Charge	(VDS = 15 V, VGS = 4.5 V, ID = 6 A)	Qg	-	9	nC
Gate-Source Charge		Qgs	-	3.2	
Gate-Drain Charge		Qgd	-	3	
Turn-On Delay Time	(VDS = 15 V, RL=1.4 Ω, ID =6 A, VGEN = 10 V, RGEN = 6 Ω)	td(on)	-	6	ns
Rise Time		tr	-	6	
Turn-Off Delay Time		td(off)	-	33	
Fall Time		tf	-	11	
Input Capacitance	(VDS = 15 V, VGS = 0 V, f = 1 Mhz)	Ciss	-	1280	pF
Output Capacitance		Coss	-	65	
Reverse Transfer Capacitance		Crss	-	53	
Gate Resistance (VDS=0V, VGS=0V, f=1.0MHz)	Rg	-	0.74	-	Ω

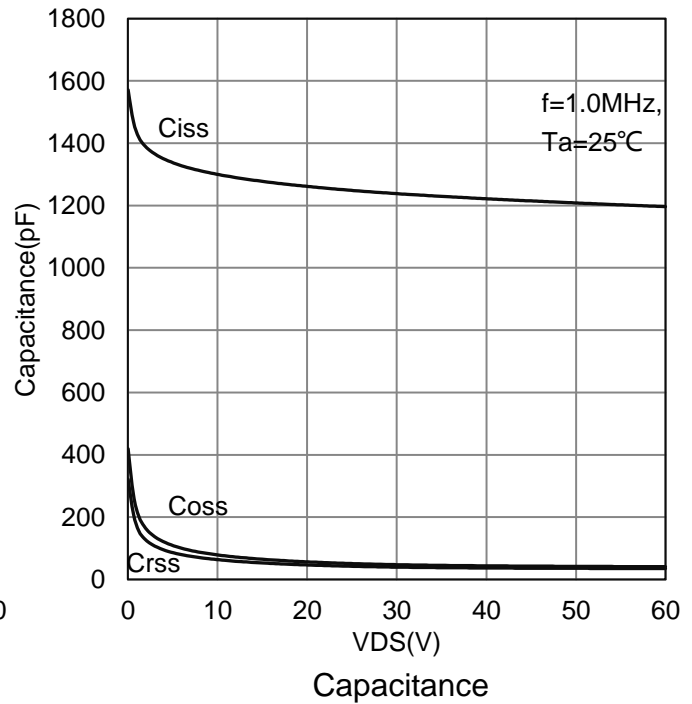
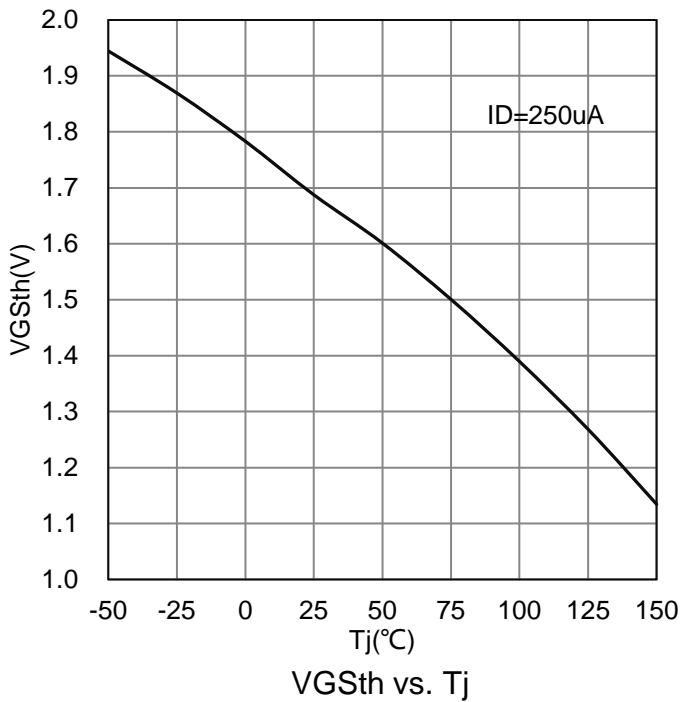
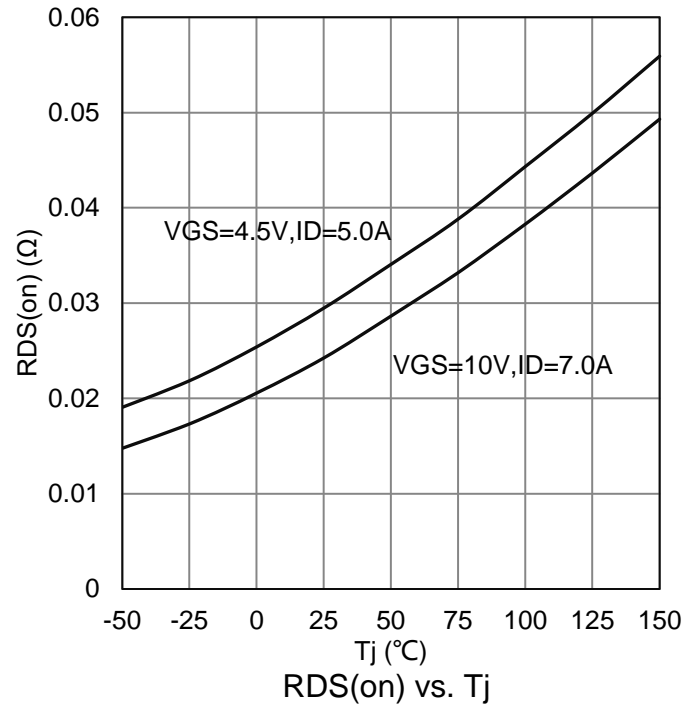
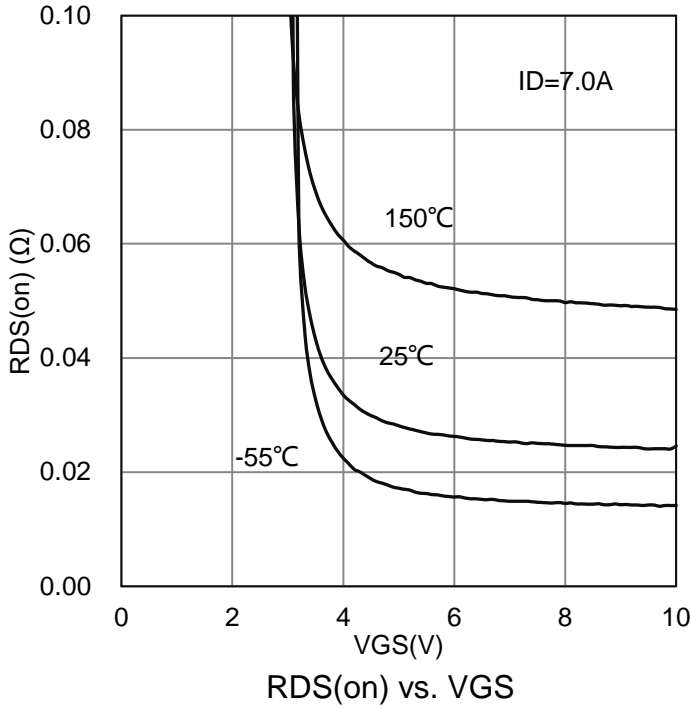
3. Pulse test: PW ≤ 300us duty cycle ≤ 2%.

4. Guaranteed by design, not subject to production testing.

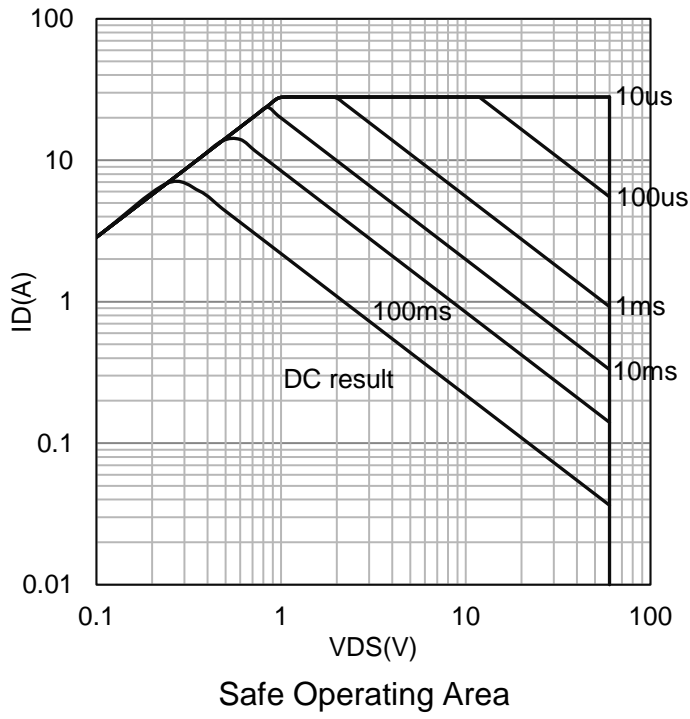
7. ELECTRICAL CHARACTERISTICS CURVES



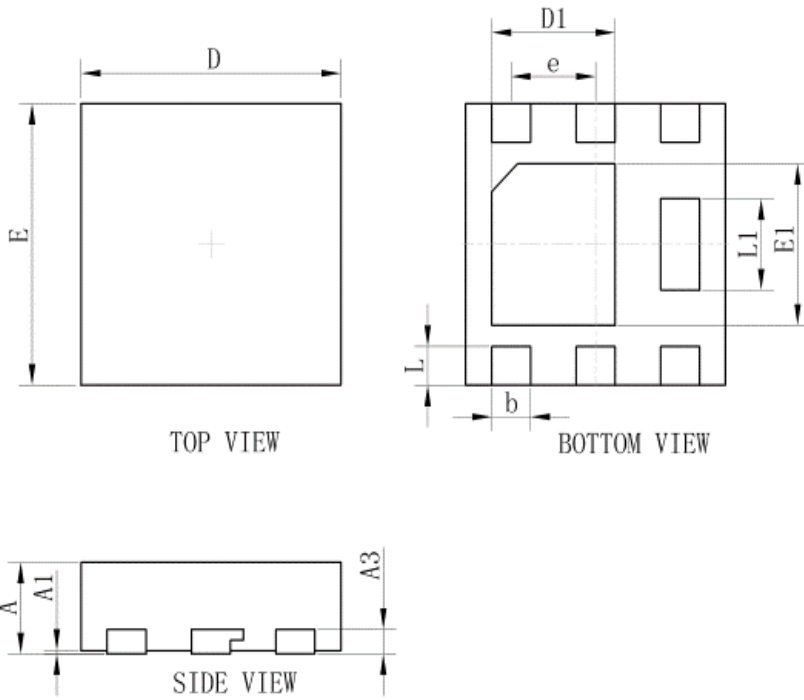
7.ELECTRICAL CHARACTERISTICS CURVES(Con.)



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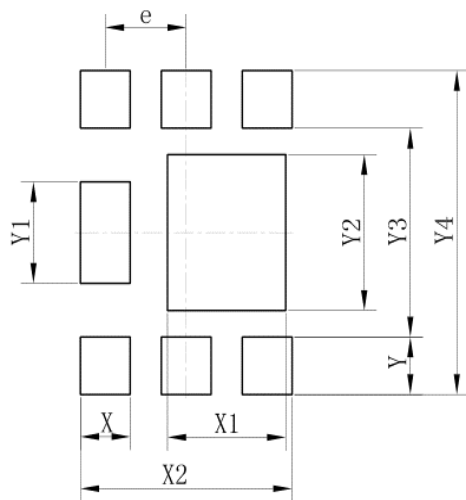


8. OUTLINE AND DIMENSIONS



DFN2020-6S			
DIM	MIN	NOR	MAX
A	0.60	0.65	0.70
A1	0.01	0.03	0.05
b	0.25	0.30	0.35
D	1.95	2.00	2.05
E	1.95	2.00	2.05
e	0.65TYP.		
L	0.23	0.28	0.33
L1	0.60	0.65	0.65
D1	0.90	0.95	1.00
E1	1.10	1.15	1.20
A3	0.152REF		
All Dimensions in mm			

9. SOLDERING FOOTPRINT



DFN2020-6S	
Dim	(mm)
X	0.40
X1	0.95
X2	1.70
e	0.65
Y	0.43
Y1	0.75
Y2	1.15
Y3	1.54
Y4	2.39

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